



Product / Package Information	
Package	BGA_ED
Body Size (mm)	25 X 25
Ball Count	576
Terminal Finish	SnPbAg

Environmental Information	
RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Metal Lid							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.41 E+00	98.50	985000	56.00	559976
Copper & its alloys	Nickel	7440-02-0	3.68 E-02	1.50	15000	0.85	8528
Subtotal	Subtotal		2.45 E+00	100.0	1000000	56.85	568504

Metal Lid Adhesive							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Alumina Filler	Proprietary	4.40 E-02	80	800000	1.02	10210
Other organic materials	Silicone Elastomer	Proprietary	1.10 E-02	20	200000	0.26	2552
Subtotal			5.50 E-02	100	1000000	1	12762

Laminate							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Glass Cross	Proprietary	3.82 E-01	38.77	387700	8.87	88703
Thermoset	Epoxy	Proprietary	3.31 E-01	33.60	336000	7.69	76875
Copper & its alloys	Copper	7440-50-8	2.11 E-01	21.42	214200	4.90	49008
Thermoset	Bromine Compounds	Proprietary	5.48 E-02	5.56	55600	1.27	12721
Other inorganic materials	Silicon Dioxide	Proprietary	6.41 E-03	0.65	6500	0.15	1487
Subtotal			9.86 E-01	100.0	1000000	23	228794

Laminate Pre-plating							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.63E-03	63.00	630000	0.04	377
Other organic materials	Lead	7439-92-1	9.55E-04	37.00	370000	0.02	222
Subtotal			2.58E-03	100.00	1000000	0.06	599

Laminate Pre-plating							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.60E-03	62.00	620000	0.04	371
Tin & its alloys	Lead	7439-92-1	9.29E-04	36.00	360000	0.02	216
Tin & its alloys	Silver	7440-22-4	5.16E-05	2.00	20000	0.001	12
Subtotal			2.58E-03	100.00	1000000	0.06	599

External Solder Ball							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.52 E-01	62.00	620000	8.17	81716
Tin & its alloys	Lead	7439-92-1	2.04 E-01	36.00	360000	4.74	47448
Tin & its alloys	Silver	7440-22-4	1.14 E-02	2.00	20000	0.26	2636
Subtotal			5.68 E-01	100	1000000	13.18	131800

Chip							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon	7440-21-3	1.84 E-01	99.0	990000	4.27	42728
Copper & its alloys	Copper	7440-50-8	1.86 E-03	1.0	10000	0.04	432
Subtotal			1.86 E-01	100	1000000	4.32	43160

High Lead Solder Bump							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Lead & its alloys	Lead	7439-92-1	2.37 E-02	97.00	41669	0.55	5492
Lead & its alloys	Tin	7440-31-5	7.32 E-04	3.00	1289	0.02	170
Subtotal			2.44 E-02	100.00	42958	0.57	5662

Underfill							
Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon dioxide filler	Proprietary	1.93 E-02	55.0	550000	0.45	4467
Other organic materials	Naphthalene Base Epoxy	Proprietary	7.00 E-03	20.0	200000	0.16	1624
Thermoset	Anhydride hardener	Proprietary	5.25 E-03	15.0	150000	0.12	1218
Others	Others	Proprietary	3.50 E-03	10.0	100000	0.08	812
Subtotal			3.50 E-02	100.0	1000000	0.81	8121

Package Totals			Weight (g)	Percentage (%)	PPM
			4.31 E+00	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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Product / Package Information

Package	BGA_ED
Body Size (mm)	25 X 25
Ball Count	576
Terminal Finish	SnAgCu with RoHS exemption

Environmental Information

RoHS Compliant	RoHS-exempt
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Metal Lid

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.41 E+00	98.50	985000	56.03	560311
Nickel & its alloys	Nickel	7440-02-0	3.68 E-02	1.50	15000	0.85	8533
Subtotal	Subtotal		2.45 E+00	100.0	1000000	56.88	568844

Metal Lid Adhesive

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Alumina Filler	Proprietary	4.40 E-02	80	800000	1.02	10216
Nickel & its alloys	Silicone Elastomer	Proprietary	1.10 E-02	20	200000	0.26	2554
Subtotal			5.50 E-02	100	1000000	1	12770

Laminate

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Glass Cross	Proprietary	3.82 E-01	38.77	387700	8.88	88756
Thermoset	Epoxy	Proprietary	3.31 E-01	33.60	336000	7.69	76921
Copper & its alloys	Copper	7440-50-8	2.11 E-01	21.42	214200	4.90	49037
Thermoset	Bromine Compounds	Proprietary	5.48 E-02	5.56	55600	1.27	12729
Other inorganic materials	Silicon Dioxide	Proprietary	6.41 E-03	0.65	6500	0.15	1488
Subtotal			9.86 E-01	100.0	1000000	23	228931

Laminate Pre-plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Lead & its alloys	Tin	7440-31-5	1.63E-03	63.00	630000	0.04	377
Lead & its alloys	Lead	7439-92-1	9.55E-04	37.00	370000	0.02	222
			2.58E-03	100.00	1000000	0.06	599

External Solder Ball

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.48 E-01	96.50	965000	12.73	127263
Tin & its alloys	Silver	7440-22-4	1.70 E-02	3.00	30000	0.40	3956
Tin & its alloys	Copper	7440-50-8	2.84 E-03	0.50	5000	0.07	659
Subtotal			5.68 E-01	100	1000000	13.19	131879

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon	7440-21-3	1.84 E-01	99.0	990000	4.28	42754
Copper & its alloys	Copper	7440-50-8	1.86 E-03	1.0	10000	0.04	432
Subtotal			1.86 E-01	100	1000000	4.32	43186

High Lead Solder Bump

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Lead & its alloys	Lead	7439-92-1	2.37 E-02	97.00	41669	0.55	5495
Lead & its alloys	Tin	7440-31-5	7.32 E-04	3.00	1289	0.02	170
Subtotal			2.44 E-02	100.00	42958	0.57	5665

Underfill

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silicon dioxide filler	Proprietary	1.93 E-02	55.0	550000	0.45	4469
Other organic materials	Naphthalene Base Epoxy	Proprietary	7.00 E-03	20.0	200000	0.16	1625
Thermoset	Anhydride hardener	Proprietary	5.25 E-03	15.0	150000	0.12	1219
Others	Others	Proprietary	3.50 E-03	10.0	100000	0.08	813
Subtotal			3.50 E-02	100.0	1000000	0.81	8126

			Weight (g)		Percentage (%)	PPM
Package Totals			4.31 E+00		100.00	1000000

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